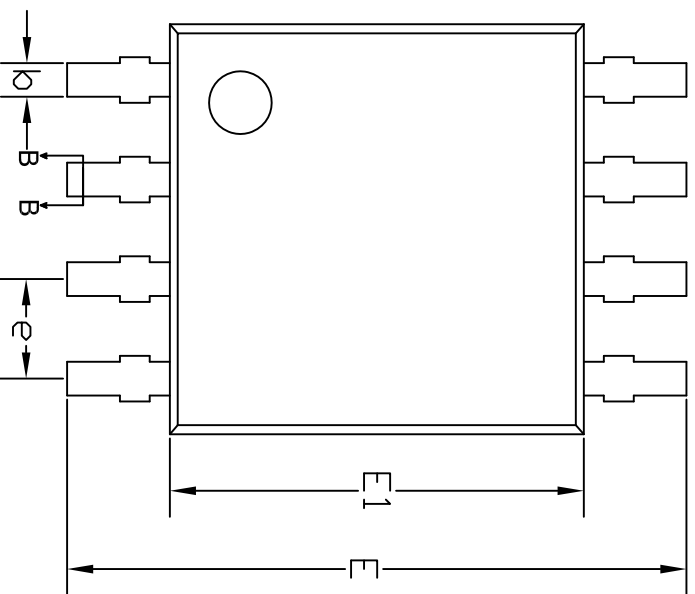
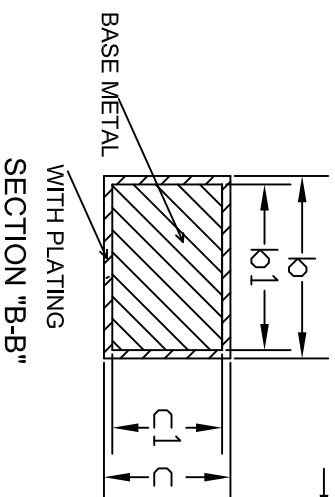
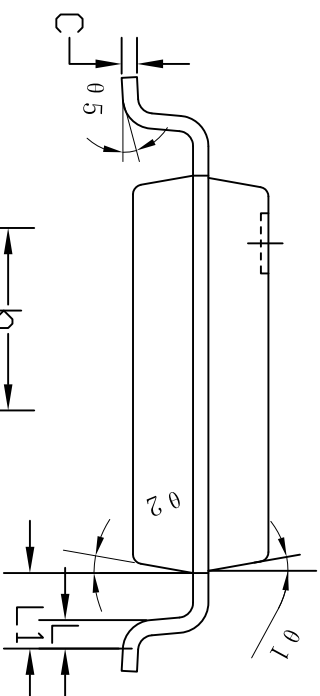
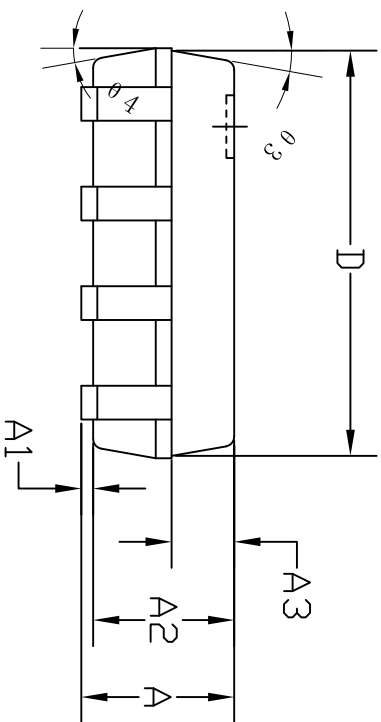




MARK	MARK	REVISION RECORD	REVISERE	APPROVER
A				
A				

SOP8(W) PACKAGE OUTLINE DIMENSIONS



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	--	--	1.95
A1	0.10	0.15	0.18
A2	1.75	1.80	1.90
A3	0.78	0.80	0.82
b	0.42	--	0.48
b1	0.40	0.44	0.48
c	0.20	--	0.24
c1	0.19	0.20	0.21
D	5.00	5.17	5.25
E	7.85	7.90	7.98
E1	5.16	5.22	5.26
e	1.27(BSC)		
L	0.60	0.65	0.70
L1	1.31(REF)		
theta_1	8°	~	12°
theta_2	8°	~	12°
theta_3	8°	~	12°
theta_4	8°	~	12°
theta_5	0°	~	6°

技术说明:

- 1) LEADFRAME MATERIAL: COPPER;
引线框架材料: 铜;
- 2) LEADFRAME THICKNESS: 0.203mm;
引线框架厚度: 0.203mm;
- 3) BOTH PACKAGE LENGTH AND WIDTH DO NOT INCLUDE MOLD FLASH;
塑封体长度及宽度尺寸不包括塑封溢胶;
- 4) REFERENCE: JEDEC MS-013, MS-012.
参考标准: JEDEC MS-013, MS-012。